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Gold/Aluminum Wedge Bonder 6400 Specifications

<i>Bond Area</i>	200 x 150mm
<i>Z-Range</i>	25mm
<i>Wire Diameter</i>	17 to 75 µm
<i>Wire Feed</i>	30°, 45° (standard), 60°; 90° deep access head optional
<i>Ultrasonic System</i>	60 kHz or 100 kHz, 140 kHz optional
<i>Pattern Recognition</i>	travelling CCD camera and Cognex
<i>Lighting</i>	3 channels, direct, indirect and side light
<i>Wire Count</i>	> 10,000
<i>Die Count</i>	200 standard
<i>Control</i>	Pentium™ processor with UNIX™-based operating system
<i>Program Storage</i>	Hard disk, floppy disk and streamer
<i>Data Transfer</i>	several standard options for export of quality control data
<i>Network Capability</i>	TCP/IP network standard built in, allowing remote access for diagnosis, service and software maintenance
<i>Quality Assurance</i>	Bond Process Control for extremely uniform bonds
<i>Dimensions (approx.)</i>	58 x 100 x 150 cm W x D x H
<i>Line Requirements</i>	100 - 260VAC, 50 - 60Hz, 3kW, single phase
<i>Air / Vacuum</i>	5 bar / 550 mm/Hg
Material Input	
<i>Substrate Size</i>	200 x 150 mm maximum
<i>Substrate Types</i>	Leadframes, PCBs, boats, carriers etc.
<i>Component Handling</i>	Manual, semi-automatic, automatic magazine to magazine or in-line
Operating Data	
<i>Position Repeatability</i>	better than +/-3µm typically
<i>Loop Lengths</i>	250µm minimum
<i>Bond Speed</i>	430ms

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